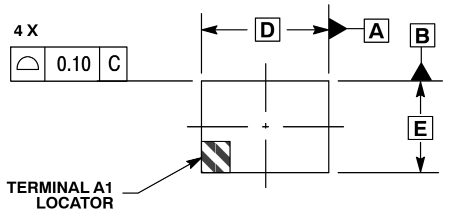
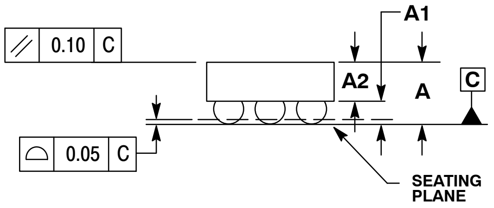
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

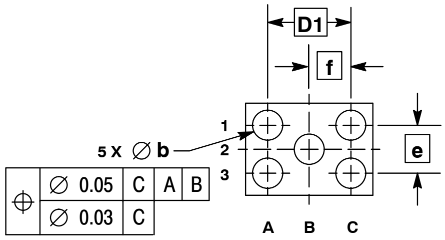
5 PIN FLIP−CHIP CSP
CASE 766AB
ISSUE O

DATE 04 JUN 2003


SCALE 4:1



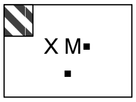




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

	MILLIMETERS	
DIM	**MIN**	**MAX**
A	---	0.680
A1	0.210	0.270
A2	0.380	0.430
D	1.330 BSC	
E	0.960 BSC	
b	0.290	0.340
e	0.500 BSC	
f	0.433 BSC	
D1	0.866 BSC	

GENERIC MARKING DIAGRAM



X = Specific Device Code
M = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

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DESCRIPTION:	**5 PIN FLIP−CHIP CSP**	**PAGE 1 OF 1**